



News Release

Unisem Reports Revenue of RM269.4 million Resulting in Net loss of RM20.2 million for Fourth Quarter 2012

Kuala Lumpur, 18 February 2013 – Unisem (M) Berhad today announced results for the fourth quarter ended 31 December 2012 (**4Q12**).

Unisem recorded a consolidated revenue of RM269.4 million (approx. US\$88.1 million) for 4Q12, which represents 4.8 percent decline from the preceding quarter (**3Q12**) and decline of 1.4 percent compared to revenue recorded in the same quarter a year ago (**4Q11**). The Group recorded a consolidated net loss of RM20.2 million (approx. US\$6.6 million) compared to net profit of RM8.3 million (approx. US\$2.7 million) in 3Q12 and net loss of RM2.5 million (approx. US\$828,000) in 4Q11.

The consolidated net loss for the quarter was mainly attributable to impairment losses on assets, provision for write-off on inventory, retrenchment costs, higher interest and depreciation charges as well as lower foreign exchange gains.

Group earnings before interest, tax, depreciation and amortization (**EBITDA**) for 4Q12 came in at about RM24.8 million (approx. US\$8.1 million), EBITDA margin was about 10 percent, compared to RM54.0 million (from approx. US\$17.2 million) in 3Q12. Equipment capacity utilization averaged at about 67 percent for the group in 4Q12. Group capital expenditure incurred in 4Q12 was about RM33.1 million (approx. US\$10.8 million), principally for purchase of equipment for advanced packaging activities for Unisem (M) Berhad and Unisem Chengdu.

Commenting on the outlook of the Group, Mr. John Chia Sin Tet, group managing director said, "The operating environment remains challenging due to global economic uncertainties. We expect a soft first quarter due to continued inventory adjustments in the industry. Our efforts to contain costs and re-align our business model will continue and we expect these to contribute and improve the performance of the Group in financial year 2013."

About Unisem

Unisem is a global provider of semiconductor assembly and test services for many of the world's most successful electronics companies. Unisem offers an integrated suite of packaging and test services such as wafer bumping, wafer probing, wafer grinding, a wide range of leadframe and substrate IC packaging, wafer level CSP and RF, analog, digital and mixed-signal test services. Our turnkey services include design, assembly, test, failure analysis, and electrical and thermal characterization. With approximately 8,500 employees worldwide, Unisem has factory locations in Ipoh, Malaysia; Wales, United Kingdom; Chengdu, People's Republic of China; Batam, Indonesia and Sunnyvale, USA. The company is headquartered in Kuala Lumpur, Malaysia. For more information about the company, its products and services, please visit its website at www.unisemgroup.com.